



**MSR  
Electronics**



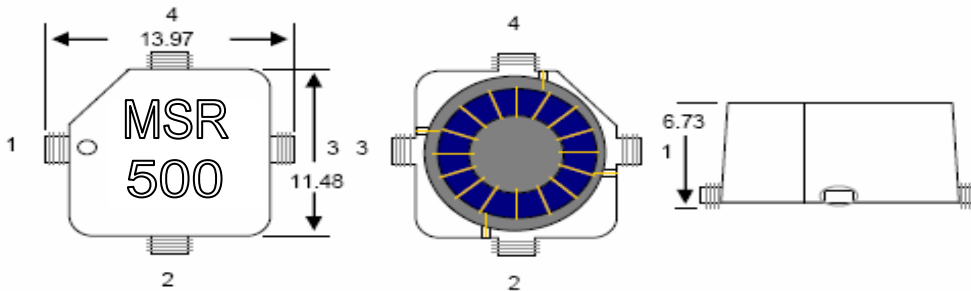
**SMD TOROIDAL POWER IND/XFMR**

**RoHS**



Compliant: Contact  
Factory for Copy of  
Test Report

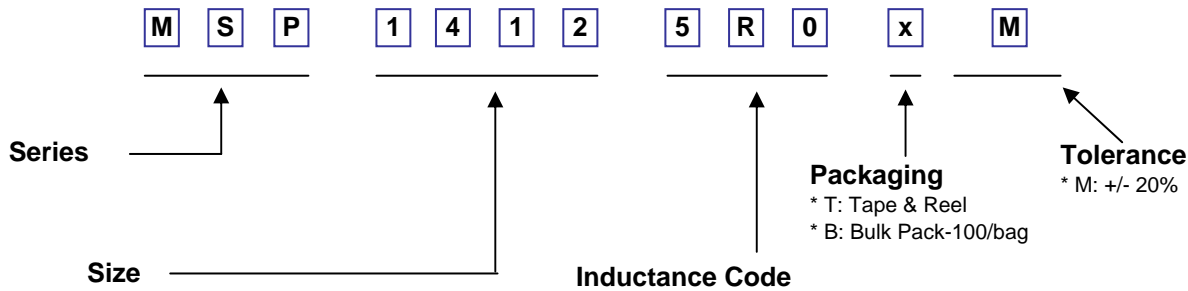
**MSP1412 SERIES**



**FEATURES:**

- Solder Heat Resistance: 260 °C @ 30 seconds
- Dimensions (mm)
- Temp Rise = 35 °C @ Irms
- L drops 10% @ Isat
- Operating Temp = -55 to +125 °C
- Spec Ratings are at 25 °C
- Parallel, Series, or Xfmr Mode
- Hipot = 500 Volts

**PART NUMBER SYSTEM**



Part Number
MSP1412-5R0xM
MSP1412-8R0xM
MSP1412-100xM
MSP1412-150xM
MSP1412-200xM
MSP1412-250xM
MSP1412-330xm
MSP1412-500xM
MSP1412-680xM
MSP1412-101xM
MSP1412-151xM
MSP1412-201xM
MSP1412-251xM
MSP1412-301xM

PARALLEL			
OCL (uH)	uH @ DC Bias	I (A)	DCR Ohms Max
5.00	3.8	3.30	0.019
8.00	5.8	3.00	0.024
10.0	7.3	2.70	0.028
15.0	11.0	2.20	0.041
20.0	14.2	2.02	0.049
25.0	17.0	1.90	0.054
33.0	23.1	1.60	0.078
50.0	35.5	1.28	0.120
68.0	46.2	1.19	0.140
100	68.0	0.98	0.210
150	103.5	0.78	0.320
200	140.0	0.65	0.470
250	172.5	0.60	0.530
300	213.0	0.52	0.730

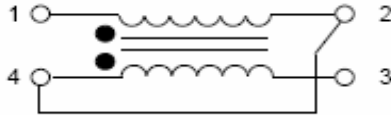
SERIES			
OCL (uH)	uH @ DC Bias	I (A)	DCR Ohms Max
20.0	15.2	1.65	0.076
32.0	23.2	1.50	0.096
40.0	29.6	1.35	0.110
60.0	44.0	1.10	0.160
80.0	56.8	1.01	0.200
100	68.0	0.96	0.220
132	92.4	0.80	0.310
200	142.0	0.64	0.480
272	185.0	0.60	0.560
400	272.0	0.49	0.840
600	414.0	0.39	1.280
800	560.0	0.33	1.880
1000	690.0	0.30	2.120
1200	852.0	0.26	2.920

# GENERAL PARAMETERS: Layout, Schematic, Packaging

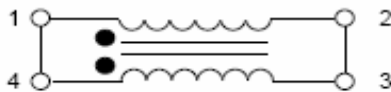
## Solder Pad

### SCHEMATICS

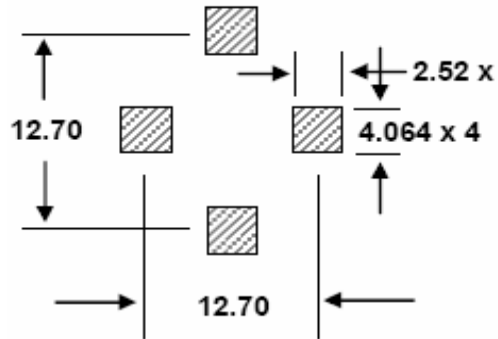
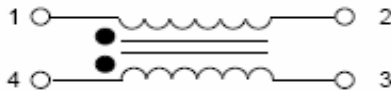
Series Mode



Parallel Mode



1:1 XFMR, Dual Diff. Mode



### PACKAGING

### LABEL

